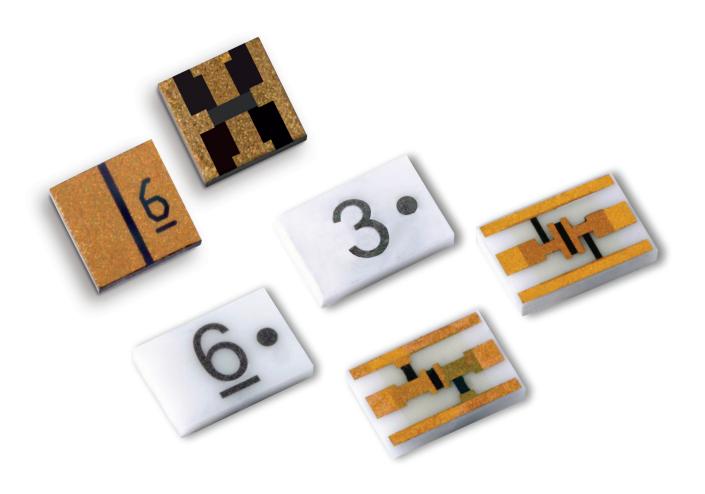
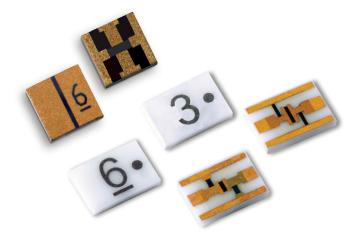
TSX Chip Attenuator Series

Fixed Chip Attenuator



TSX Series



Smiths Interconnect is a leading provider of chip attenuators offering the widest selection of products from DC to Q-band, backed by proven performance and significant heritage. Chip components are offered on Alumina, Aluminum Nitride, Beryllium Oxide, and CVD Diamond for a wide range of applications.

The TSX Series of chip attenuators pushes the boundaries of Size, Weight and Power in a cost effective, easy to implement surface mount or wire bondable solution, suitable for a wide array of applications. The TSX Series offers excellent broadband RF performance to 50 GHz while delivering increased power handling in a solder mount or chip and wire form factor.

The chip attenuator design offers 1 to 3 watts of power handling performance and multiple attenuation values are available for surface mounting. The use of a robust, proven all thin film process technology on an alumina substrate provides a product suitable for harsh environments, such as those of Space and Defense applications.



TSX Chip
Attenuators offer
excellent performance
and power from
DC-50 GHz in a
small 0604 or 0404
package size.

Features and Benefits

- Small form factor Reduces overall footprint
- Surface mountable or wire bondable Ideal for pick and place or chip and wire applications
- Broad frequency range Reduces BOM count
- Low VSWR Increases transmitted power
- Wide range of attenuation values 1-10, 15 and 20dB
- Tight attenuation tolerance For optimal performance

Applications

- Amplifier Circuits
- Transmit/Receive Modules
- Up/Down Converters
- Instrumentation
- Satellite Communications
- Radar
- 5G

Technical Characteristics

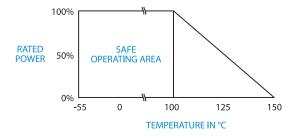
Mounting Configuration Options	Planar									
Electrical										
Nominal Impedance	50 ohms									
Frequency Range	DC - 50 GHz									
Attenuation Values	0-10, 15 & 20 dB in 1 dB Increments									
Attenuation Accuracy	ATTENUATION ACCURACY (dB)									
	Atter Valu	nuation e (dB)	DC-4	0 GHz						
		0		Continuity Only						
	1	-10	±	0.50	± 0.5					
	15	& 20	±	0.50	±	3.0				
Input Power CW			INPUT PO	OWER (CW)						
	dB	Watts	dB	Watts	dB	Watts				
	0-1	3.0	2-3	2.0	4-20	1.0				
Peak Power	10X CW power t	oased on 1 μS pulse	width @ 1% Duty	Cycle						
			VSWR	(Typical)						
	dB		DC-4	10 GHz	40-50 GHz					
	0			Continu	uity Only					
	1-10		1.20	:1 Max	1.25:1 Max					
	15	5-20	1.20	:1 Max	1.25:1 Max					
Environmental										
Operating Temperature	-55°C to +150°C									
Storage Temperature	-65°C to +150°C									
Temperature Coefficient	±200 PPM/°C Max									
Moisture Sensitivity Level	MSL 1 - Unlimited									
Mechanical										
Substrate Material	Alumina (Al ₂ O ₃)	96%								
Resistive Film	Thin Film, Tantalum Nitride									
Terminal Material	Thin Film, Solde	rable Gold over Nick	cel							
Protective Coating	Silicon Nitride									
Marking										
Unit Marking	Orientation dot and dB Value									
Quality Assurance										
	Sample visual ar	nd mechanical inspe	ction - 1.0 AQL p	er mechanical drawii	ng requirements.					
	Periodic electrica	al inspection perforn	ned for commeric	al grade products.						
	High reliability to	ested products are a	vailable per MIL-P	RF-55342.						
Packaging										
Standard Packaging	Tape and Reel o	r Waffle Pack								

2

Technical Characteristics

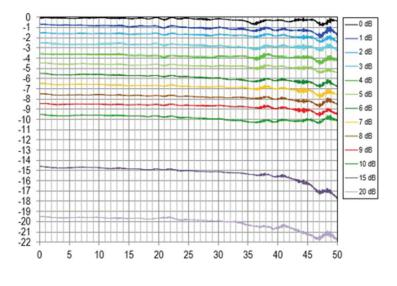
Mounting Configuration Options	WB2										
Electrical											
Nominal Impedance	50 ohms										
Frequency Range	DC - 50 GHz										
Attenuation Values	0-10, 15, 20 & 30dB in 1 dB Increments										
Attenuation Accuracy	ATTENUATION ACCURACY (dB)										
	Attenuation DC-20 GHz 20-40 GHz							40-50 GHz			
	0				Continuity O	nly					
	1-10			± 0.50	± 0.75	± 0.75					
	15, 20 & 30	0		± 0.50	± 0.75			± 3.00			
Input Power CW	INPUT POWER (CW)										
	dB	Wa	tts	dB	Watts	Watts d		Watts			
	O-1	3	.0	2-3	2.0	2.0 4-		1.0			
Peak Power	10X CW power based on 1 µS pulse width @ 1% Duty Cycle										
				VSWR (Typical)						
	dB		DC-20 GHz		20-40 GHz		40-50 GHz				
VSWR	0				Continuity Only						
	1-3		1.25:1 Max		1.35:1 Max		1.50:1 Max				
	4-6		1.25:1 Max		1.35:1 Max		1.50:1 Max				
Environmental			ı				ı				
Operating Temperature	-55°C to +150°C										
Storage Temperature	-65°C to +150°C										
Temperature Coefficient	±200 PPM/°C Max										
Moisture Sensitivity Level	MSL 1 - Unlimited										
Mechanical											
Substrate Material	Aluminum Nitride										
Resistive Film	Thin Film, Tantal	um Nitride	9								
Terminal Material	Thin Film, Bondable Gold										
Protective Coating	N/A										
Marking											
Unit Marking	dB Value on ground plane										
Quality Assurance											
	Sample visual and mechanical inspection - 1.0 AQL per mechanical drawing requirements.										
	Periodic electrical inspection performed for commerical grade products.										
	High reliability tested products are available per MIL-PRF-55342.										
Packaging											
Standard Packaging	Tape and Reel or Waffle Pack										

Power Derating Curve

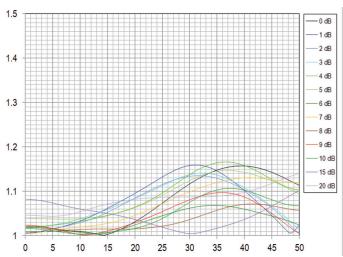


Typical Data

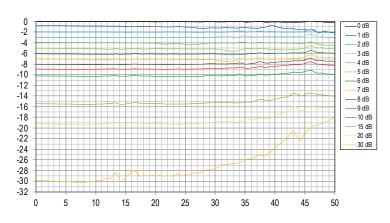
TSX Planar Series Attenuation



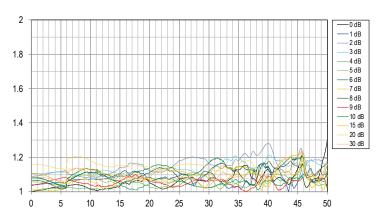
TSX Planar Series VSWR



TSX WB2 Series Attenuation

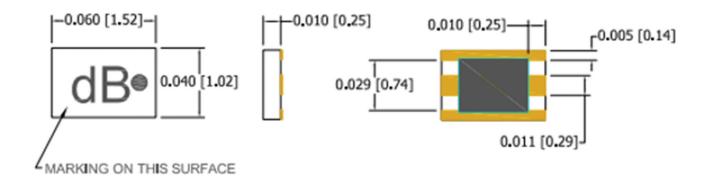


TSX WB2 Series VSWR



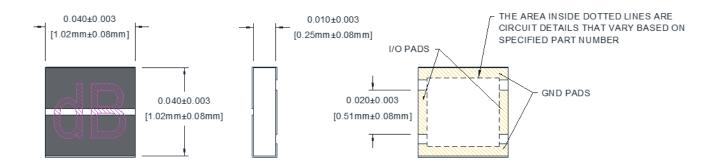
Mechanical

TSX Planar Series



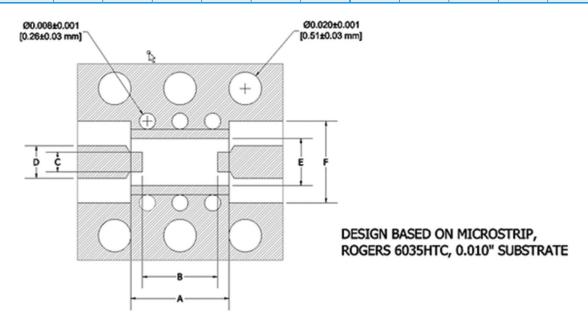
Mechanical

TSX WB2 Series



Suggested Mounting Footprint

	Inches					Inches Millimeters						
Part Number	Α	В	С	D	Е	F	Α	В	С	D	Е	F
TSXdB.00	0.060	0.046	0.012	0.020	0.029	0.050	1.52	1.17	0.30	0.51	0.74	1.27



How To Order

Specify Model Number: TSXdB.00

TSX		. 0 0					
1	2	3	4				
1 Series Name	T S X Series						
2 Attenuation Value	0 0 00 dB through 10.0 dB 1 5 15.0 dB 2 0 20.0 dB						
3 SINT Code	. O O Smiths						
4 Options	Solderable W B 2 Wire b	ondable					

Worldwide Support

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